

Features

• Split Gate Trench MOSFET technology

- Excellent package for heat dissipation
- High density cell design for low R_{DS(ON)}

Product Summary

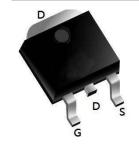


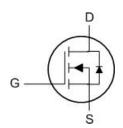
BVDSS	RDSON	ID
120V	85mΩ	12A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

TO252-3L Pin Configuration





Absolute Maximum Ratings (T_C= 25°C unless otherwise specified):

			<u> </u>	
Symbol	Parameter		Value	Units
V _{DSS}	Drain-to-Source Voltage	120	V	
I_	Continuous Drain Current	T _C = 25 °C	12	Α
I _D	Continuous Drain Current	T _C = 100 °C	8.7	Α
I _{DM} ^{a1}	Pulsed Drain Current		60	Α
E _{AS} ^{a2}	Single pulse avalanche energy		22	mJ
V_{GS}	Gate-to-Source Voltage		±20	V
P _D	Power Dissipation		46	W
тт	Operating Junction and Stora	150 55 to 150	°C	
T _J , T _{STG}	Temperature Range		150, –55 to 150	
TL	Maximum Temperature for Solo	260	$^{\circ}\mathrm{C}$	

Thermal Characteristics:

Symbol	Parameter	Value	Units
Rejc	Thermal Resistance, Junction-to-Case	2.7	°C/W



Electrical Characteristics (T_J= 25°C unless otherwise specified):

Static Characteristics								
Symbol	Parameter	Test Conditions		Units				
Syllibol	Farameter	rest Conditions	Min.	Тур.	Max.	Ullits		
V _{DSS}	Drain to Source Breakdown Voltage	V_{GS} =0 V , I_D =250 μ A	120			٧		
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 100V, V _{GS} = 0V	1		1	μΑ		
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =-20V			100	nA		
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =+20V			-100	nA		
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.3	1.8	2.3	V		
R _{DS(ON)}	Drain-to-	V_{GS} =10 V , I_{D} =5 A		85	105	$m\Omega$		
	Source On-	V_{GS} =4.5 V , I_{D} =4 A		100	130	mΩ		
	Resistance							

Dynamic Characteristics									
Symbol	Parameter	Test Conditions	Value			Units			
Syllibol	Parameter		Min.	Тур.	Max.	Ullits			
C _{iss}	Input Capacitance	\/ -0\/		248	-				
Coss	Output Capacitance	V _{GS} =0V V _{DS} =50V	1	60	-	pF			
C _{rss}	Reverse Transfer Capacitanc	f=1.0MHz		2.0		Pi			

Resistiv	Resistive Switching Characteristics								
Symbol	Develope	Test Conditions		Value					
Symbol	Parameter	rest Conditions	Min.	Тур.	Max.	Units			
t _{d(ON)}	Turn-on Delay Time	I _D =10A, R _L =0.75Ω		9					
tr	Rise Time	V _{DS} =50V		18		no			
$t_{d(OFF)}$	Turn-Off Delay Time	V _{GS} = 10V		19		ns			
t _f	Fall Time	$R_G=3\Omega$		16					
Qg	Total Gate Charge	V _{GS} =10V		3.8					
Qgs	Gate Source Charge	V _{DS} =50V		0.9		nC			
Q_{gd}	Gate Drain Charge	I _D =10A		1					

Source-E	Source-Drain Diode Characteristics								
Symbol	Danama atau	Test Conditions	Value			115:45			
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units			
Is	Diode Forward Current	T _C =25 °C			12	Α			
V _{SD}	Diode Forward Voltage	I _S =0.5A,V _{GS} =0V			1.2	V			
t _{rr}	Reverse Recovery time	I ₀ =10Λ \/ ₀₀ =50\/		24		ns			
Q _{rr}	Reverse Recovery Charge	I _S =10A, V _{DD} =50V dI/dt=100A/μs		20		nC			

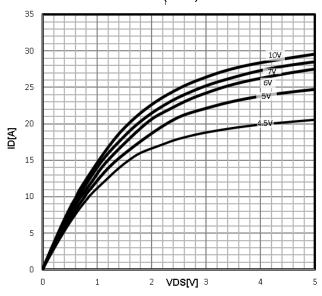
^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

 $^{^{}a2}\colon$ L=5mH, Rg=25\Omega, Starting TJ=25 $^{\circ}\mathrm{C}$

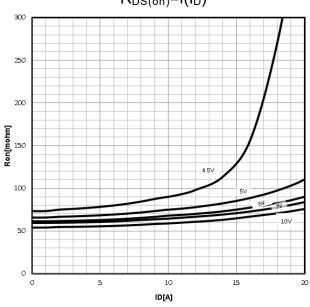


Characteristics Curve:

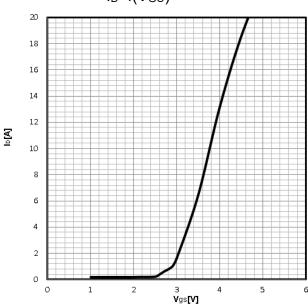
Typ. output characteristics $I_D=f(V_{DS})$



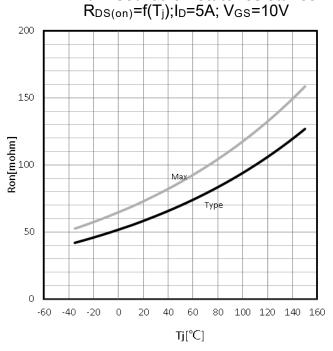
Typ. drain-source on resistance $R_{DS(on)}=f(I_D)$



Typ. transfer characteristics $I_D=f(V_{GS})$

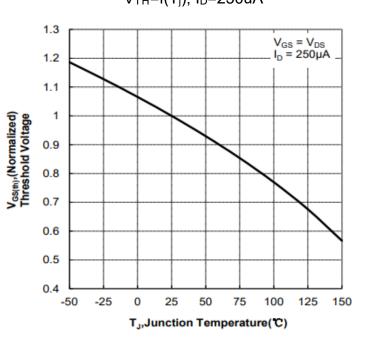


Drain-source on-state resistance



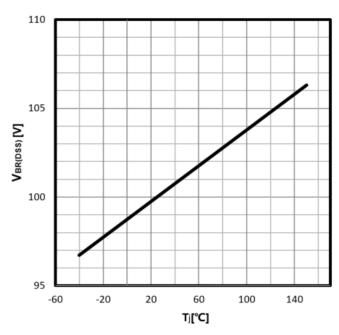


Gate Threshold Voltage V_{TH} = $f(T_j)$; I_D =250uA

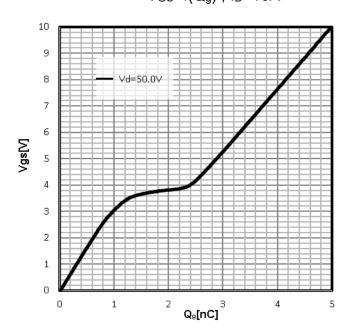


Drain-source breakdown voltage

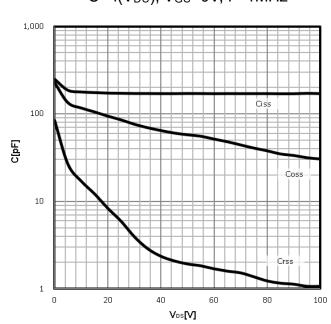
 $V_{BR(DSS)}=f(T_j); I_D=250uA$



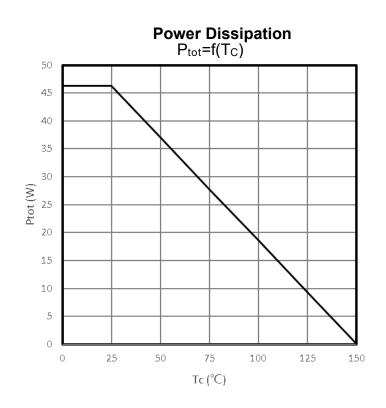
Typ. gate charge V_{GS} =f(Q_g); I_D =10A

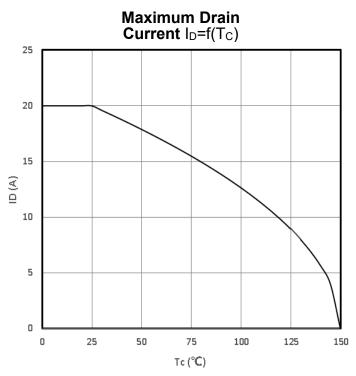


Typ. capacitances $C = f(V_{DS})$; $V_{GS} = 0V$; f = 1MHz

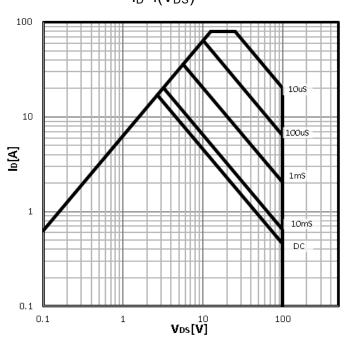




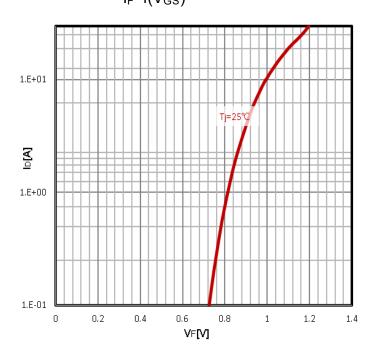




Safe operating area $I_D = f(V_{DS})$



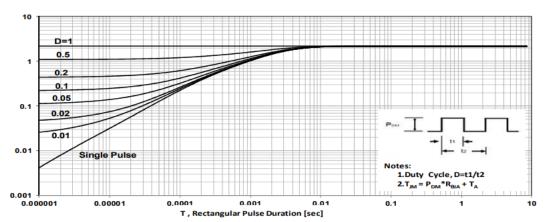
Body Diode Forward Voltage Variation $I_F = f(V_{GS})$





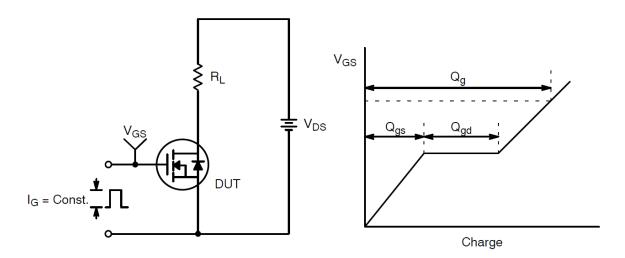
Max. transient thermal impedance



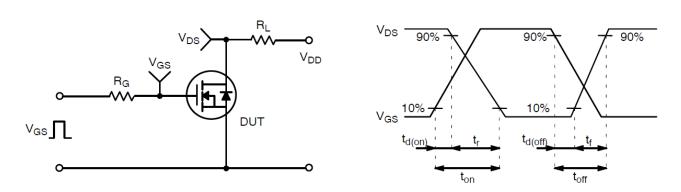




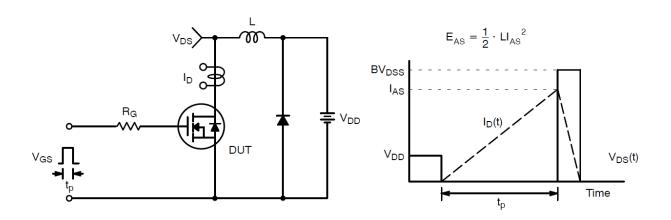
Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform



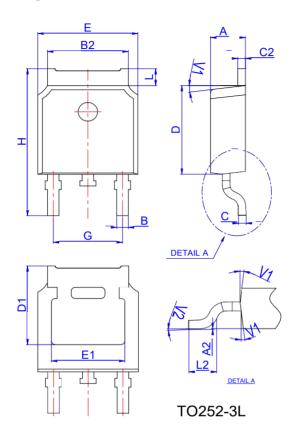
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

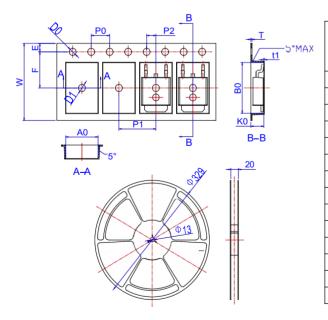


Package Mechanical Data TO252-3L



	Dimensions						
Ref.		Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			().209REF		
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	

Reel Spectification-TO252-3L



	Dimensions							
Ref.		Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
W	15.90	16.00	16.10	0.626	0.630	0.634		
Е	1.65	1.75	1.85	0.065	0.069	0.073		
F	7.40	7.50	7.60	0.291	0.295	0.299		
D0	1.40	1.50	1.60	0.055	0.059	0.063		
D1	1.40	1.50	1.60	0.055	0.059	0.063		
P0	3.90	4.00	4.10	0.154	0.157	0.161		
P1	7.90	8.00	8.10	0.311	0.315	0.319		
P2	1.90	2.00	2.10	0.075	0.079	0.083		
A0	6.85	6.90	7.00	0.270	0.271	0.276		
В0	10.45	10.50	10.60	0.411	0.413	0.417		
K0	2.68	2.78	2.88	0.105	0.109	0.113		
Т	0.24		0.27	0.009		0.011		
t1	0.10			0.004				
10P0	39.80	40.00	40.20	1.567	1.575	1.583		